# **CNA1303K** (ON1003)

### Photo Interrupter

For contactless SW, object detection

#### Overview

CNA1302K is an ultraminiature, highly reliable transmissive photosensor in which a high efficiency GaAs infrared light emitting diode chip and a high sensitivity Si phototransistor chip are integrated in a double molded resin package.

#### Features

• Ultraminiature: 4.2 mm × 4.2 mm (height: 5.2 mm)

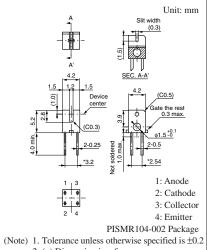
• Fast response:  $t_r$ ,  $t_f = 35 \mu s$  (typ.)

• Highly precise position detection: 0.15 mm

• Gap width: 1.2 mm

#### ■ Absolute Maximum Ratings $T_a = 25$ °C

	Symbol	Rating	Unit	
Input (Light	Reverse voltage	$V_R$	6	V
emitting diode)	Forward current	$I_F$	50	mA
	Power dissipation *1	$P_{\mathrm{D}}$	75	mW
Output (Photo	Collector-emitter voltage	V <sub>CEO</sub>	35	V
transistor)	(Base open)			
	Emitter-collector voltage	V <sub>ECO</sub>	6	V
	(Base open)			
	Collector current	$I_C$	20	mA
	Collector power dissipation *2	P <sub>C</sub>	75	mW
Temperature	Operating ambient temperature	Topr	-25 to +85	°C
	Storage temperature	T <sub>stg</sub>	-40 to +100	°C



2. ( ) Dimension is reference

3. \* is dimension at the root of leads

4. Burrs should be less than 0.15 mm

- Note) \*1: Input power derating ratio is 1.0 mW/°C at  $T_a \ge 25^{\circ}C$ .

> \*2: Output power derating ratio is 1.0 mW/°C at  $T_a \ge 25$ °C.

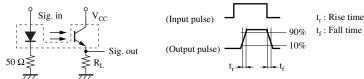
### ■ Electrical-Optical Characteristics $T_a = 25$ °C $\pm 3$ °C

	Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Input	Forward voltage	$V_{\rm F}$	$I_F = 20 \text{ mA}$		1.2	1.4	V
characteristics	Reverse current	$I_R$	$V_R = 3 V$			10	μΑ
Output	Collector-emitter cutoff current	$I_{CEO}$	$V_{CE} = 20 \text{ V}$			100	nA
characteristics	(Base open)						
Transfer	Collector current	$I_C$	$V_{CE} = 5 \text{ V}, I_F = 5 \text{ mA}$	100		1 300	μΑ
characteristics	Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_F = 10 \text{ mA}, I_C = 40 \mu\text{A}$			0.4	V
	Rise time *	t <sub>r</sub>	$V_{CC} = 5 \text{ V}, I_{C} = 0.1 \text{ mA}$		35		μs
	Fall time *	$t_{\rm f}$	$R_L = 1000\Omega$		35		μs

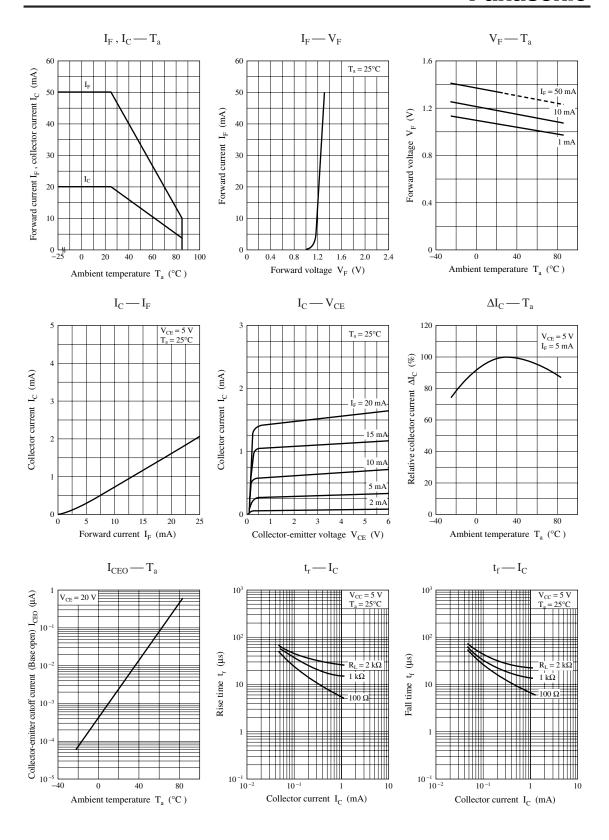
Note) 1. Input and output are practiced by electricity.

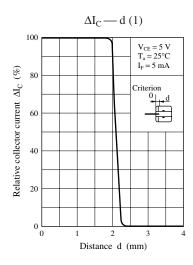
2. This device is designed be disregarded radiation.

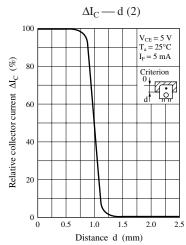
3. \*: Switching time measurement circuit



Note) The part number in the parenthesis shows conventional part number.







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## ■ This product contains Gallium Arsenide (GaAs).

GaAs powder and vapor are hazardous to human health if inhaled or ingested. Do not burn, destroy, cut, cleave off, or chemically dissolve the product. Follow related laws and ordinances for disposal. The product should be excluded from general industrial waste or household garbage.

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